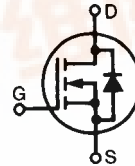




HiPerFET™ Power MOSFETs

IXFK 24N100
IXFX 24N100

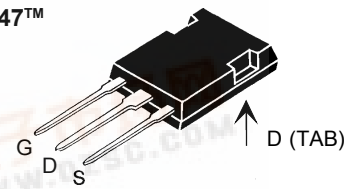
Single MOSFET Die



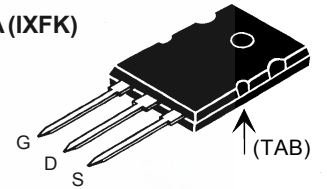
$$\begin{aligned} V_{DSS} &= 1000 \text{ V} \\ I_{D25} &= 24 \text{ A} \\ R_{DS(on)} &= 0.39 \Omega \\ t_{rr} &\leq 250 \text{ ns} \end{aligned}$$

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	1000	V
V_{DGR}	$T_J = 25^\circ\text{C}$ to 150°C ; $R_{GS} = 1 \text{ M}\Omega$	1000	V
V_{GS}	Continuous	± 20	V
V_{GSM}	Transient	± 30	V
I_{D25}	$T_C = 25^\circ\text{C}$	24	A
I_{DM}	$T_C = 25^\circ\text{C}$, Note 1	96	A
I_{AR}	$T_C = 25^\circ\text{C}$	24	A
E_{AR}	$T_C = 25^\circ\text{C}$	60	mJ
E_{AS}	$T_C = 25^\circ\text{C}$	3	J
dv/dt	$I_S \leq I_{DM}$, $di/dt \leq 100 \text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$ $T_J \leq 150^\circ\text{C}$, $R_G = 2 \Omega$	5	V/ns
P_D	$T_C = 25^\circ\text{C}$	560	W
T_J		-55 ... +150	$^\circ\text{C}$
T_{JM}		150	$^\circ\text{C}$
T_{stg}		-55 ... +150	$^\circ\text{C}$
T_L	1.6 mm (0.063 in.) from case for 10 s	300	$^\circ\text{C}$
M_d	Mounting torque	TO-264	0.9/6 Nm/lb.in.
Weight	PLUS 247		6 g
	TO-264		10 g

**PLUS 247™
(IXFX)**



TO-264 AA (IXFK)



G = Gate
S = Source

D = Drain
TAB = Drain

Features

- International standard packages
- Low $R_{DS(on)}$ HDMOS™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
 - easy to drive and to protect
- Fast intrinsic rectifier

Applications

- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- AC motor control
- Temperature and lighting controls

Advantages

- PLUS 247™ package for clip or spring mounting
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
V_{DSS}	$V_{GS} = 0 \text{ V}$, $I_D = 3 \text{ mA}$	1000		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 8 \text{ mA}$	3.0		5.0 V
I_{GSS}	$V_{GS} = \pm 20 \text{ V}$, $V_{DS} = 0$			$\pm 100 \text{ nA}$
I_{DSS}	$V_{DS} = V_{DSS}$, $V_{GS} = 0 \text{ V}$			100 μA 2 mA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$, $I_D = 0.5 \cdot I_{D25}$ Note 2			0.39 Ω

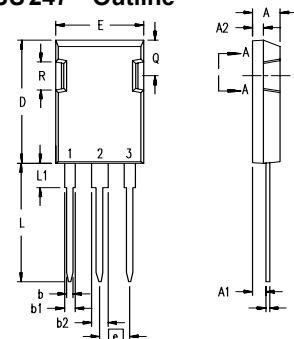


Symbol	Test Conditions		Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
			min.	typ.	max.
g_{fs}	$V_{DS} = 10\text{ V}; I_D = 0.5 \cdot I_{D25}$	Note 2	15	22	S
C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$			7000	pF
C_{oss}				750	pF
C_{rss}				260	pF
$t_{d(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 1\ \Omega$ (External),			35	ns
t_r				35	ns
$t_{d(off)}$				75	ns
t_f				21	ns
$Q_{g(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$			250	nC
Q_{gs}				55	nC
Q_{gd}				135	nC
R_{thJC}				0.22	K/W
R_{thCK}			0.15		K/W

Symbol	Test Conditions		Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
			min.	typ.	max.
I_S	$V_{GS} = 0\text{ V}$			24	A
I_{SM}	Repetitive; pulse width limited by T_{JM}			96	A
V_{SD}	$I_F = I_S, V_{GS} = 0\text{ V}$, Note 1			1.5	V
t_{rr}	$I_F = I_S, -di/dt = 100\text{ A}/\mu\text{s}, V_R = 100\text{ V}$			250	ns
Q_{RM}				1.0	μC
I_{RM}				8	A

Note: 1. Pulse width limited by T_{JM}
2. Pulse test, $t \leq 300\ \mu\text{s}$, duty cycle $d \leq 2\%$

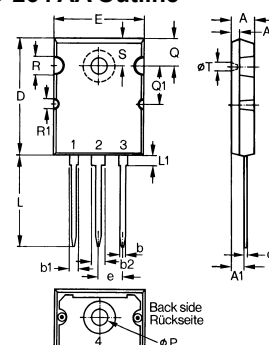
PLUS 247™ Outline



Terminals: 1 - Gate
2 - Drain (Collector)
3 - Source (Emitter)
4 - Drain (Collector)

Dim.	Millimeter Min. Max.	Inches Min. Max.
A	4.83 5.21	.190 .205
A ₁	2.29 2.54	.090 .100
A ₂	1.91 2.16	.075 .085
b	1.14 1.40	.045 .055
b ₁	1.91 2.13	.075 .084
b ₂	2.92 3.12	.115 .123
C	0.61 0.80	.024 .031
D	20.80 21.34	.819 .840
E	15.75 16.13	.620 .635
e	5.45 BSC	.215 BSC
L	19.81 20.32	.780 .800
L ₁	3.81 4.32	.150 .170
Q	5.59 6.20	.220 .244
R	4.32 4.83	.170 .190

TO-264 AA Outline



Dim.	Millimeter Min. Max.	Inches Min. Max.
A	4.82 5.13	.190 .202
A ₁	2.54 2.89	.100 .114
A ₂	2.00 2.10	.079 .083
b	1.12 1.42	.044 .056
b ₁	2.39 2.69	.094 .106
b ₂	2.90 3.09	.114 .122
c	0.53 0.83	.021 .033
D	25.91 26.16	1.020 1.030
E	19.81 19.96	.780 .786
e	5.46 BSC	.215 BSC
J	0.00 0.25	.000 .010
K	0.00 0.25	.000 .010
L	20.32 20.83	.800 .820
L ₁	2.29 2.59	.090 .102
P	3.17 3.66	.125 .144
Q	6.07 6.27	.239 .247
Q ₁	8.38 8.69	.330 .342
R	3.81 4.32	.150 .170
R ₁	1.78 2.29	.070 .090
S	6.04 6.30	.238 .248
T	1.57 1.83	.062 .072

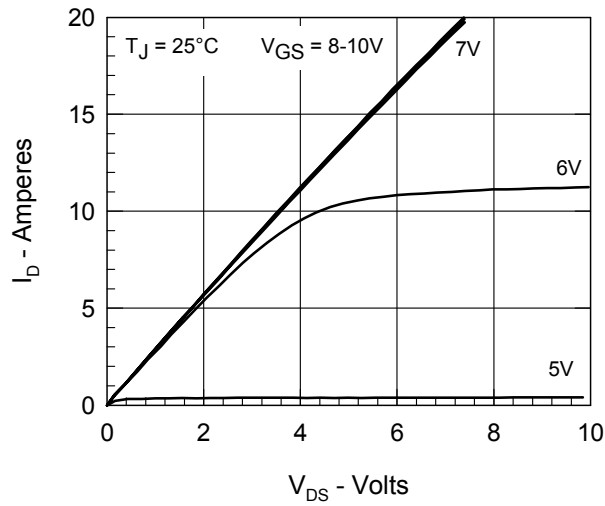


Fig.1 Output Characteristics @ $T_J = 25^\circ\text{C}$

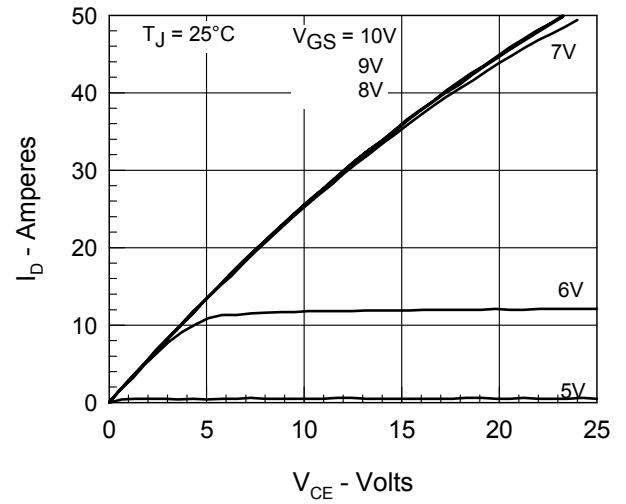


Fig.2 Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

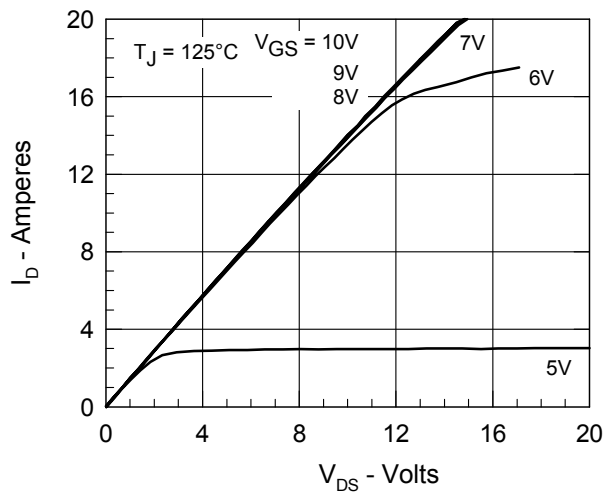


Fig.3 Output Characteristics @ $T_J = 25^\circ\text{C}$

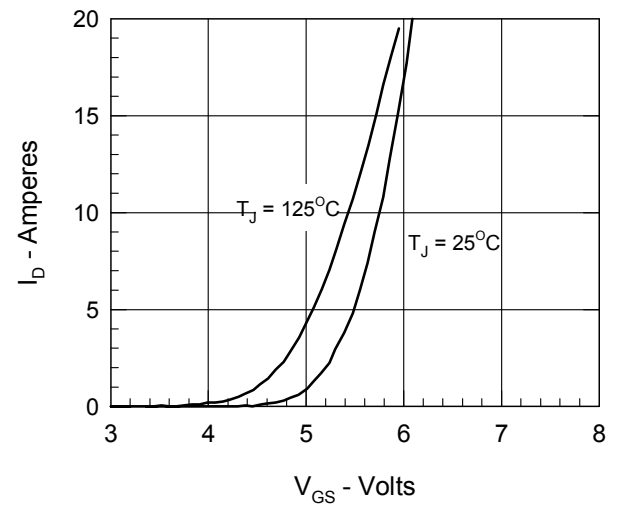


Fig.4 Drain Current vs Gate Source Voltage

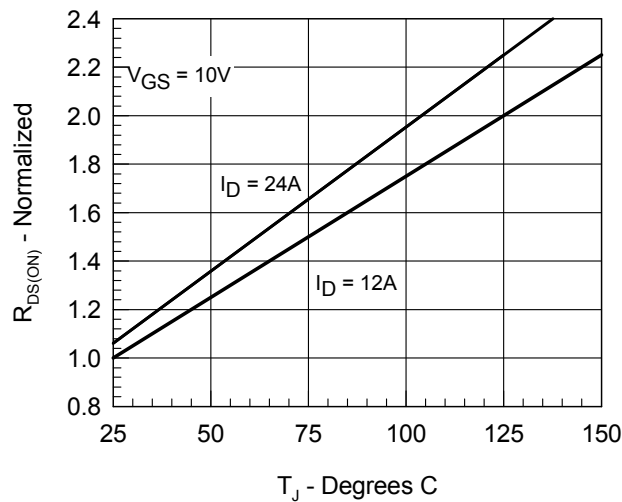


Fig.5 Temperature Dependence of Drain-to-

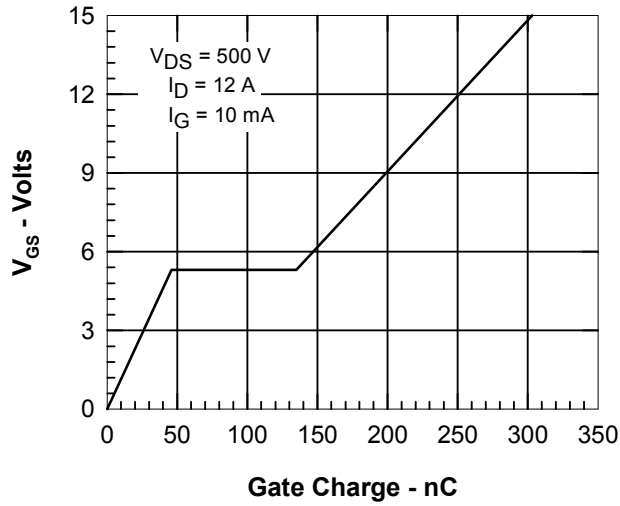


Fig. 6 Gate Charge Characteristic

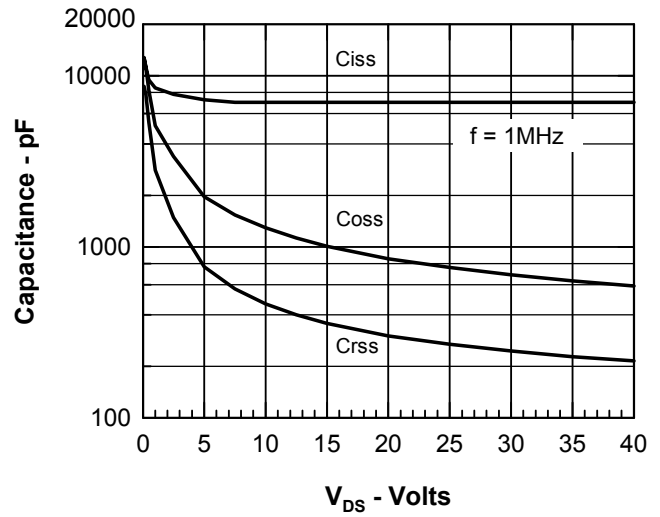


Fig. 7 Capacitance Curves

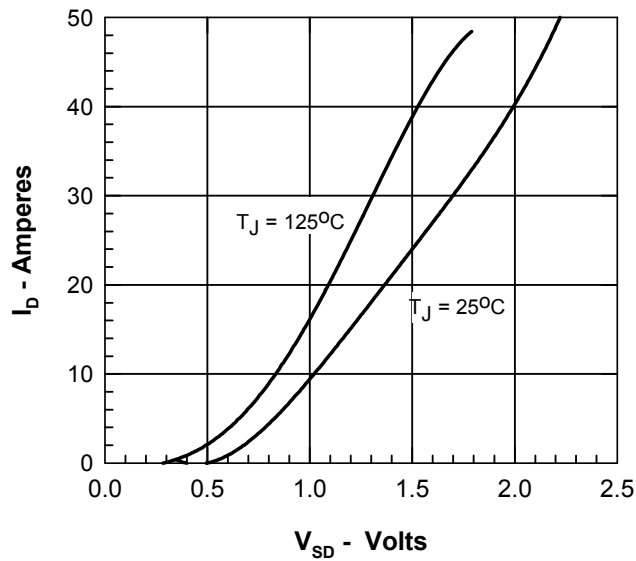


Fig. 8 Drain Current vs Drain to Source Voltage

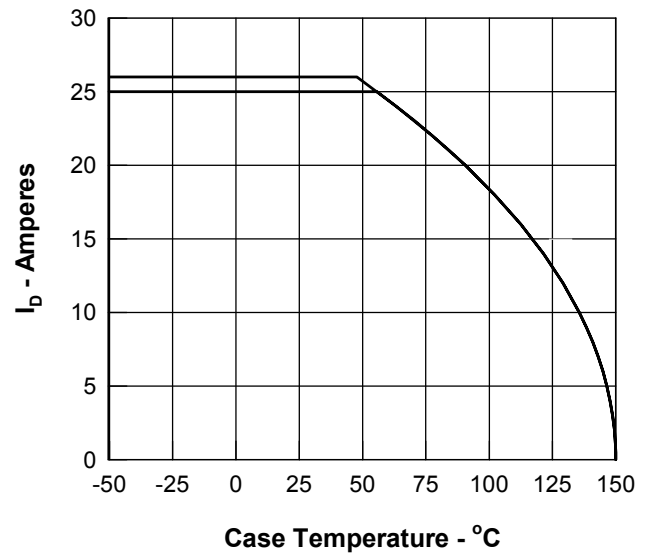


Fig. 9 Drain Current vs Case Temperature

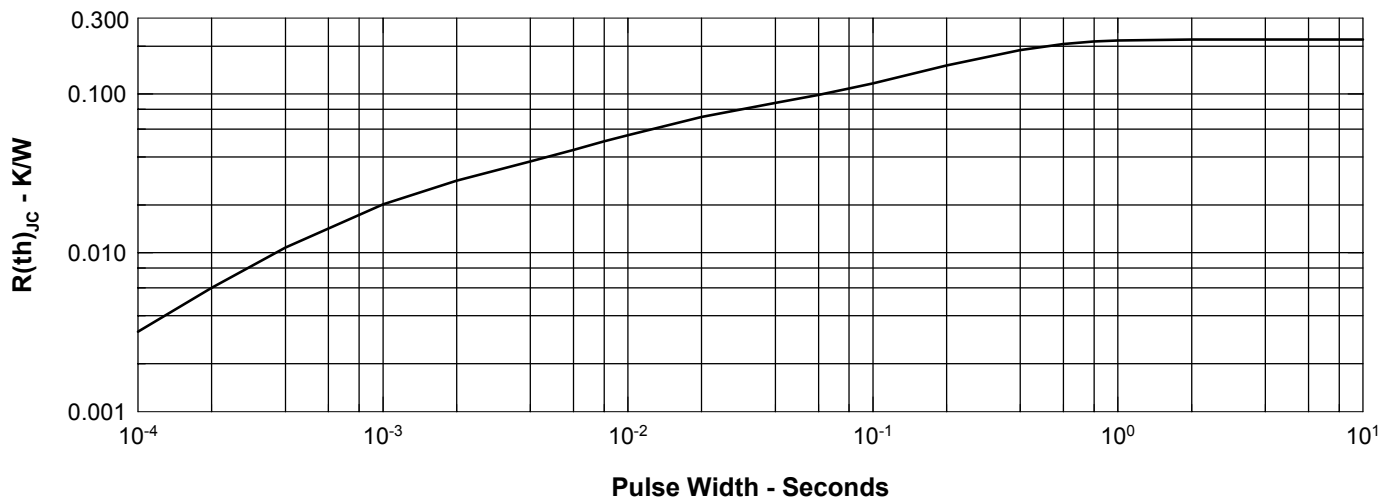


Fig. 10 Transient Thermal Resistance